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PRODUCT DATA SHEET

SikaBond[®] AT-80

Easily spread, elastic wood flooring adhesive

PRODUCT DESCRIPTION

SikaBond[®] AT-80 is a 1-component, solvent-free, wood flooring adhesive with very good workability.

USES

SikaBond[®] AT-80 is designed for full surface bonding of solid and engineered wood floors, mosaic parquet, industrial parquet, lam parquet, residential wood floors and paving, as well as chipboard floor systems and subfloors.

SikaBond® AT-80 is designed for use with most common types of wood floors.

CHARACTERISTICS / ADVANTAGES

- Adhesive can be sanded
- Floors can be sanded after 24 hours
- Elastic, footfall-sound dampening properties
- Suitable for use with underfloor heating
- Very low emissions
- Reduces stress transfer between the wood floor and the substrate

ENVIRONMENTAL INFORMATION

EMICODE EC1 R

PRODUCT INFORMATION

Chemical Base	Silane terminated polymers	
Packaging	17 kg plastic pail	
Colour	Parquet brown	
Shelf Life	SikaBond [®] AT-80 has a shelf life of 12 months from the date of production if it is stored properly in undamaged, original, sealed packaging, and if the storage conditions are met.	
Storage Conditions	SikaBond [®] AT-80 shall be stored in dry conditions, protected from direct sunlight and at temperatures between +5 °C and +25 °C.	
Density	1.65 kg/l approx.	

TECHNICAL INFORMATION

Shore A Hardness	40 approx. (after 28 days)	(ISO 868)
Tensile Strength	1.4 N/mm ² approx.	(ISO 37)
Elongation at Break	160% approx.	(ISO 37)
Shear Strength	1.3 N/mm ² approx., 1 mm adhesive thickness	(ISO 17178)
Service Temperature	+5 °C to +40 °C	

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APPLICATION INFORMATION

	For substrates primed with Sika® Primer MR Fast or Sika® Primer MB, the consumption of SikaBond® AT-80 may be reduced.	
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Sag Flow	SikaBond® AT-80 spreads very easily whilst maintaining stable trowel marks.	
Ambient Air Temperature	+15 °C to +35 °C	
Relative Air Humidity	40% to 70%	
Substrate Temperature	During laying and until SikaBond® AT-80 has fully cured, the substrate and ambient temperatures shall be between +15 °C and +35 °C without and between +20 °C and +35 °C with underfloor heating.	
Substrate Moisture Content	 Permissible substrate moisture content without underfloor heating: 2.5% CM for cement screeds. 0.5% CM for anhydrite screeds. 3-12% CM for magnetite flooring (depending on the organic content). Permissible substrate moisture content for use with underfloor heating: 1.8% CM for cement screeds. 0.3% CM for anhydrite screeds. 3-12% CM for magnetite flooring (depending on the organic content). Note: For all moisture contents, the quality of the substrates and surfaces, always follow the guidelines of the wood flooring manufacturer 	
Curing Rate	3.0 mm/24 hours approx. (23 °C / 50% r.h.)	
Skin Time / Laying Time	75 minutes approx. (23 °C / 50% r.h.)	

APPLICATION INSTRUCTIONS

For the application of SikaBond[®] AT-80 all standard construction guidelines apply. For further information, please refer to the Method Statement "Full Surface Bonding".

SUBSTRATE PREPARATION

- The substrate must be clean, dry, sound and homogeneous, free from oils, grease, dust and loose or friable particles. Paint, cement laitance and other poorly adhering contaminants must be removed.
- Concrete and/or cement screeds must be ground and thoroughly cleaned with an industrial vacuum.
- Anhydrite screeds, including flowable anhydrite screeds must be ground and thoroughly cleaned with an industrial vacuum shortly before bonding with the adhesive starts.
- Broadcast mastic asphalt must be primed with Sika[®]

Primer MR Fast or Sika[®] Primer MB. For the instructions for use, please refer to the corresponding Product Data Sheet.

- Glazed ceramic and old existing ceramic tiles must be degreased and cleaned with Sika[®] Aktivator-205, or the tile surfaces must be ground and then thoroughly cleaned with an industrial vacuum.
- Wood and/or gypsum boards (e.g. chipboard, plywood) must be glued and/or screwed to the substructure in order to be fixed to the substrate. For floating dry-floors, contact our Technical Service Department.
- For other substrates contact our Technical Service Department for advice and assistance.
- SikaBond[®] AT-80 can be used without priming on cement based floors, anhydrite floors, chipboards, concrete and ceramic tiles.
- For broadcasted mastic asphalt, cement based floors with excessive moisture content and use over old adhesive residues or on weak substrates use Sika[®]

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APPLICATION METHOD / TOOLS

SikaBond[®] AT-80 is applied directly from the pail to properly prepared substrates and uniformly spread with a notched trowel.

Press the wood floor pieces firmly into the adhesive so that the wood floor underside is completely covered with the adhesive. The pieces can then be joined together using a hammer and an impact block. Many types of wood floors also have to be tapped into position from above. A distance of 10–15 mm from the wall to the wood floor must be maintained. The floor shall be walked on and/or sanded 24 to 48 hours after installation (23 °C / 50% r.h. up to 1 mm adhesive thickness depending on the environmental conditions and adhesive layer thickness). Fresh, uncured adhesive on the wood floor surface must be removed immediately with a clean cloth and if necessary also cleaned with Sika® Remover-208 or Sika®TopClean-T. Always test wood floor surfaces for compatibility with Sika® Cleaner-208 before use. The guidelines of the wood floor manufacturer apply.

CLEANING OF TOOLS

Clean all tools and application equipment immediately after use with Sika[®] Remover-208 and/or Sika[®] Top-Clean T. Once cured, residual material can only be removed mechanically.

FURTHER DOCUMENTS

- Safety Data Sheet
- Pre-treatment Chart Sealing and Bonding
- Method Statement "Full Surface Bonding"

LIMITATIONS

- SikaBond[®] AT-80 is only suitable for use by professional wood floor applicators.
- For good workability, the adhesive temperature shall be ≥ +15 °C.
- For proper curing of the adhesive, sufficient ambient humidity / moisture is necessary.
- Before wood floors may be installed in non-insulated areas, such as basements or other areas without a damp proof membrane, Sikafloor® EpoCem must be applied and sealed with Sika® Primer MB to control the moisture. For detailed instructions, contact our Technical Service Department.
- For use with chemically pre-treated types of wood floors (e.g. those produced or treated with ammonia, wood stain, timber preservative) and woods with a relatively high oil content, SikaBond® AT-80 is only to be used with the written agreement of our Technical Service Department.
- Do not use on polyethylene (PE), polypropylene (PP), polytetrafluoroethylene (PTFE / Teflon), and other similar plasticized synthetic materials.
- Some other floor priming materials can negatively influence the adhesion of SikaBond[®] AT-80 (pre-trials recommended).
- SikaBond[®] AT-80 is designed as a wood floor bonding adhesive. When laying parquet type wood floors without tongued and grooved joints, e.g. mosaic par-

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- Avoid contact between any wood surface sealer coatings and adhesive. However, if direct contact with the adhesive is unavoidable, then the compatibility must be checked and confirmed before use of any coatings. For further information and advice, please contact our Technical Service Department.
- Do not expose uncured SikaBond[®] AT-80 to alcohol containing products as they may interfere with the curing reaction.
- For further information and advice, please contact our Technical Service Department.

VALUE BASE

All technical data stated in this Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

LOCAL RESTRICTIONS

Note that as a result of specific local regulations the declared data and recommended uses for this product may vary from country to country. Consult the local Product Data Sheet for exact product data and uses.

ECOLOGY, HEALTH AND SAFETY

User must read the most recent corresponding Safety Data Sheets (SDS) before using any products. The SDS provides information and advice on the safe handling, storage and disposal of chemical products and contains physical, ecological, toxicological and other safety-related data.

LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must

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be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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